

74AUP1G58

Low-power configurable multiple function gate

Rev. 5 — 29 November 2011

Product data sheet

1. General description

The 74AUP1G58 provides configurable multiple functions. The output state is determined by eight patterns of 3-bit input. The user can choose the logic functions AND, OR, NAND, NOR, XOR, inverter and buffer. All inputs can be connected to V_{CC} or GND.

This device ensures a very low static and dynamic power consumption across the entire V_{CC} range from 0.8 V to 3.6 V.

This device is fully specified for partial power-down applications using I_{OFF} . The I_{OFF} circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

The 74AUP1G58 has Schmitt trigger inputs making it capable of transforming slowly changing input signals into sharply defined, jitter-free output signals.

The inputs switch at different points for positive and negative-going signals. The difference between the positive voltage V_{T+} and the negative voltage V_{T-} is defined as the input hysteresis voltage V_H .

2. Features and benefits

- Wide supply voltage range from 0.8 V to 3.6 V
- High noise immunity
- ESD protection:
 - ◆ HBM JESD22-A114F exceeds 5000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
 - ◆ CDM JESD22-C101E exceeds 1000 V
- Low static power consumption; $I_{CC} = 0.9 \mu\text{A}$ (maximum)
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- Inputs accept voltages up to 3.6 V
- Low noise overshoot and undershoot < 10 % of V_{CC}
- I_{OFF} circuitry provides partial power-down mode operation
- Multiple package options
- Specified from $-40 \text{ }^\circ\text{C}$ to $+85 \text{ }^\circ\text{C}$ and $-40 \text{ }^\circ\text{C}$ to $+125 \text{ }^\circ\text{C}$



3. Ordering information

Table 1. Ordering information

| Type number | Package | | | Version |
|-------------|-------------------|-------|---|---------|
| | Temperature range | Name | Description | |
| 74AUP1G58GW | -40 °C to +125 °C | SC-88 | plastic surface-mounted package; 6 leads | SOT363 |
| 74AUP1G58GM | -40 °C to +125 °C | XSON6 | plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm | SOT886 |
| 74AUP1G58GF | -40 °C to +125 °C | XSON6 | plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1 × 0.5 mm | SOT891 |
| 74AUP1G58GN | -40 °C to +125 °C | XSON6 | extremely thin small outline package; no leads; 6 terminals; body 0.9 × 1.0 × 0.35 mm | SOT1115 |
| 74AUP1G58GS | -40 °C to +125 °C | XSON6 | extremely thin small outline package; no leads; 6 terminals; body 1.0 × 1.0 × 0.35 mm | SOT1202 |

4. Marking

Table 2. Marking

| Type number | Marking code ^[1] |
|-------------|-----------------------------|
| 74AUP1G58GW | aK |
| 74AUP1G58GM | aK |
| 74AUP1G58GF | aK |
| 74AUP1G58GN | aK |
| 74AUP1G58GS | aK |

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram

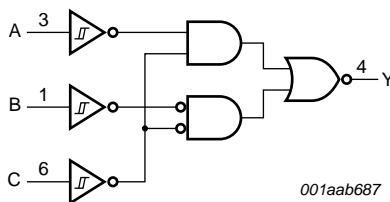
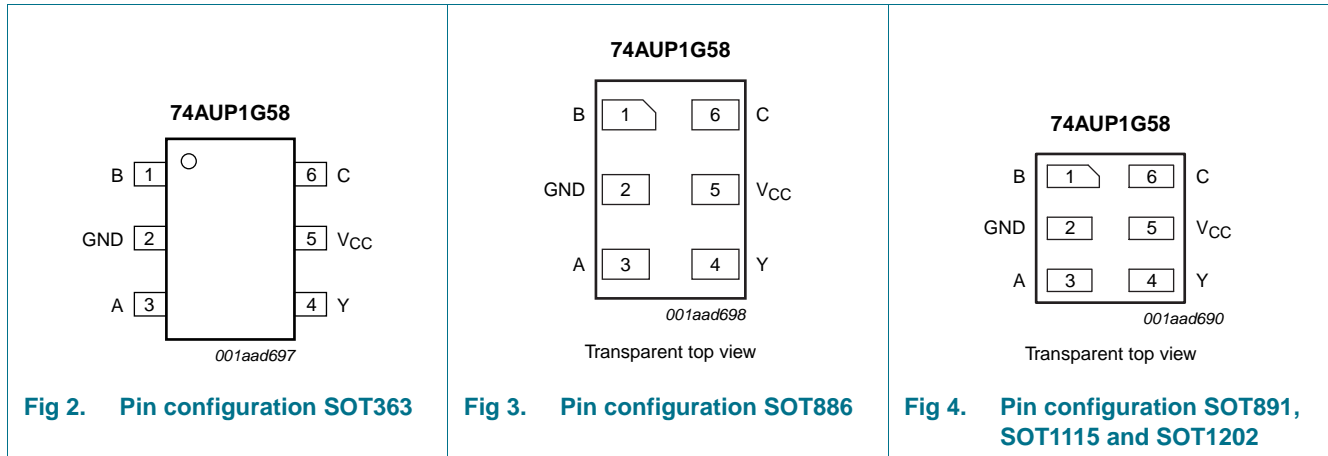


Fig 1. Logic symbol

6. Pinning information

6.1 Pinning



6.2 Pin description

Table 3. Pin description

| Symbol | Pin | Description |
|-----------------|-----|----------------|
| B | 1 | data input |
| GND | 2 | ground (0 V) |
| A | 3 | data input |
| Y | 4 | data output |
| V _{CC} | 5 | supply voltage |
| C | 6 | data input |

7. Functional description

Table 4. Function table^[1]

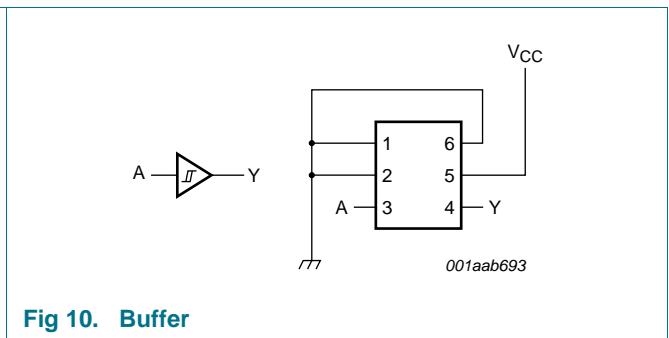
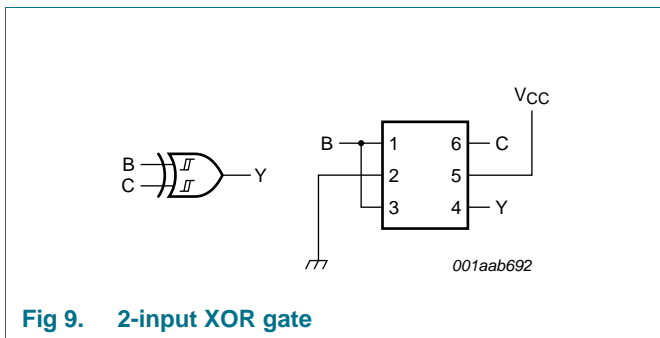
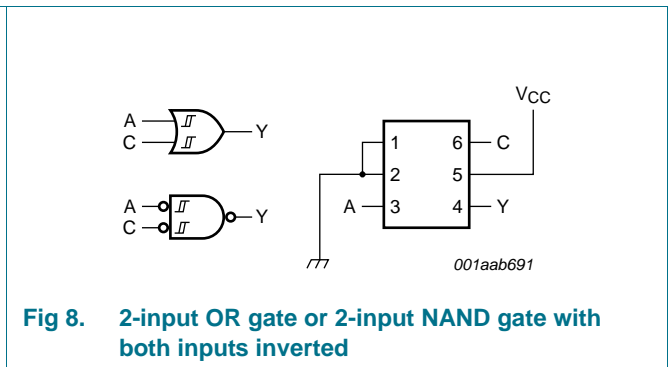
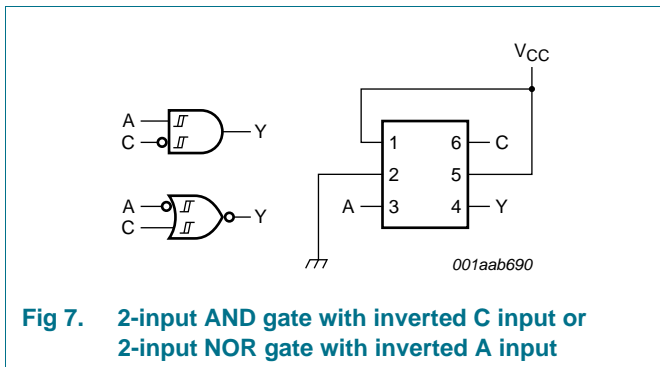
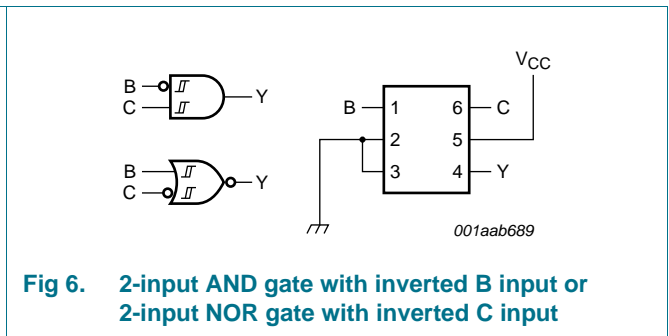
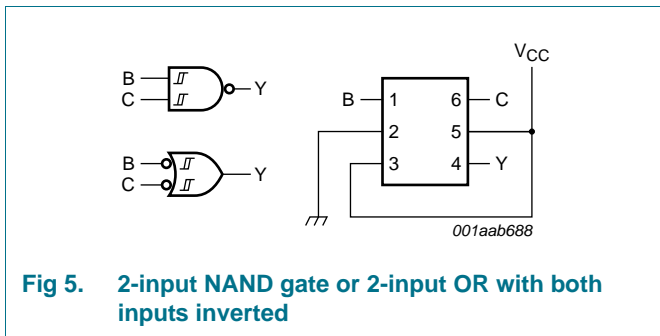
| Input | | | Output |
|-------|---|---|--------|
| C | B | A | Y |
| L | L | L | L |
| L | L | H | H |
| L | H | L | L |
| L | H | H | H |
| H | L | L | H |
| H | L | H | H |
| H | H | L | L |
| H | H | H | L |

[1] H = HIGH voltage level; L = LOW voltage level.

7.1 Logic configurations

Table 5. Function selection table

| Logic function | Figure |
|--|---|
| 2-input NAND | see Figure 5 |
| 2-input NAND with both inputs inverted | see Figure 8 |
| 2-input AND with inverted input | see Figure 6 and Figure 7 |
| 2-input NOR with inverted input | see Figure 6 and Figure 7 |
| 2-input OR | see Figure 8 |
| 2-input OR with both inputs inverted | see Figure 5 |
| 2-input XOR | see Figure 9 |
| Buffer | see Figure 10 |
| Inverter | see Figure 11 |



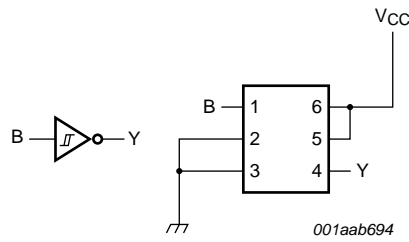


Fig 11. Inverter

8. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|-------------------------|---------------------------------|----------|----------|------|
| V_{CC} | supply voltage | | -0.5 | +4.6 | V |
| I_{IK} | input clamping current | $V_I < 0$ V | -50 | - | mA |
| V_I | input voltage | | [1] -0.5 | +4.6 | V |
| I_{OK} | output clamping current | $V_O < 0$ V | -50 | - | mA |
| V_O | output voltage | Active mode and Power-down mode | [1] -0.5 | +4.6 | V |
| I_O | output current | $V_O = 0$ V to V_{CC} | - | ± 20 | mA |
| I_{CC} | supply current | | - | 50 | mA |
| I_{GND} | ground current | | -50 | - | mA |
| T_{stg} | storage temperature | | -65 | +150 | °C |
| P_{tot} | total power dissipation | $T_{amb} = -40$ °C to +125 °C | [2] - | 250 | mW |

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SC-88 packages: above 87.5 °C the value of P_{tot} derates linearly with 4.0 mW/K.
 For XSON6 packages: above 118 °C the value of P_{tot} derates linearly with 7.8 mW/K.

9. Recommended operating conditions

Table 7. Recommended operating conditions

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|---------------------|---------------------------------|-----|----------|------|
| V_{CC} | supply voltage | | 0.8 | 3.6 | V |
| V_I | input voltage | | 0 | 3.6 | V |
| V_O | output voltage | Active mode | 0 | V_{CC} | V |
| | | Power-down mode; $V_{CC} = 0$ V | 0 | 3.6 | V |
| T_{amb} | ambient temperature | | -40 | +125 | °C |

10. Static characteristics

Table 8. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|--------------------------------------|--|------------------------|-----|-----------------------|------|
| T_{amb} = 25 °C | | | | | | |
| V _{OH} | HIGH-level output voltage | V _I = V _{T+} or V _{T-} | | | | |
| | | I _O = -20 µA; V _{CC} = 0.8 V to 3.6 V | V _{CC} - 0.1 | - | - | V |
| | | I _O = -1.1 mA; V _{CC} = 1.1 V | 0.75 × V _{CC} | - | - | V |
| | | I _O = -1.7 mA; V _{CC} = 1.4 V | 1.11 | - | - | V |
| | | I _O = -1.9 mA; V _{CC} = 1.65 V | 1.32 | - | - | V |
| | | I _O = -2.3 mA; V _{CC} = 2.3 V | 2.05 | - | - | V |
| | | I _O = -3.1 mA; V _{CC} = 2.3 V | 1.9 | - | - | V |
| | | I _O = -2.7 mA; V _{CC} = 3.0 V | 2.72 | - | - | V |
| | | I _O = -4.0 mA; V _{CC} = 3.0 V | 2.6 | - | - | V |
| V _{OL} | LOW-level output voltage | V _I = V _{T+} or V _{T-} | | | | |
| | | I _O = 20 µA; V _{CC} = 0.8 V to 3.6 V | - | - | 0.1 | V |
| | | I _O = 1.1 mA; V _{CC} = 1.1 V | - | - | 0.3 × V _{CC} | V |
| | | I _O = 1.7 mA; V _{CC} = 1.4 V | - | - | 0.31 | V |
| | | I _O = 1.9 mA; V _{CC} = 1.65 V | - | - | 0.31 | V |
| | | I _O = 2.3 mA; V _{CC} = 2.3 V | - | - | 0.31 | V |
| | | I _O = 3.1 mA; V _{CC} = 2.3 V | - | - | 0.44 | V |
| | | I _O = 2.7 mA; V _{CC} = 3.0 V | - | - | 0.31 | V |
| | | I _O = 4.0 mA; V _{CC} = 3.0 V | - | - | 0.44 | V |
| I _I | input leakage current | V _I = GND to 3.6 V; V _{CC} = 0 V to 3.6 V | - | - | ±0.1 | µA |
| I _{OFF} | power-off leakage current | V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V | - | - | ±0.2 | µA |
| ΔI _{OFF} | additional power-off leakage current | V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V to 0.2 V | - | - | ±0.2 | µA |
| I _{CC} | supply current | V _I = GND or V _{CC} ; I _O = 0 A; V _{CC} = 0.8 V to 3.6 V | - | - | 0.5 | µA |
| ΔI _{CC} | additional supply current | V _I = V _{CC} - 0.6 V; I _O = 0 A; V _{CC} = 3.3 V | - | - | 40 | µA |
| C _I | input capacitance | V _I = GND or V _{CC} ; V _{CC} = 0 V to 3.6 V | - | 1.1 | - | pF |
| C _O | output capacitance | V _O = GND; V _{CC} = 0 V | - | 1.8 | - | pF |
| T_{amb} = -40 °C to +85 °C | | | | | | |
| V _{OH} | HIGH-level output voltage | V _I = V _{T+} or V _{T-} | | | | |
| | | I _O = -20 µA; V _{CC} = 0.8 V to 3.6 V | V _{CC} - 0.1 | - | - | V |
| | | I _O = -1.1 mA; V _{CC} = 1.1 V | 0.7 × V _{CC} | - | - | V |
| | | I _O = -1.7 mA; V _{CC} = 1.4 V | 1.03 | - | - | V |
| | | I _O = -1.9 mA; V _{CC} = 1.65 V | 1.30 | - | - | V |
| | | I _O = -2.3 mA; V _{CC} = 2.3 V | 1.97 | - | - | V |
| | | I _O = -3.1 mA; V _{CC} = 2.3 V | 1.85 | - | - | V |
| | | I _O = -2.7 mA; V _{CC} = 3.0 V | 2.67 | - | - | V |
| | | I _O = -4.0 mA; V _{CC} = 3.0 V | 2.55 | - | - | V |

Table 8. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|--------------------------------------|--|------------------------|-----|------------------------|------|
| V _{OL} | LOW-level output voltage | V _I = V _{T+} or V _{T-} | | | | |
| | | I _O = 20 μA; V _{CC} = 0.8 V to 3.6 V | - | - | 0.1 | V |
| | | I _O = 1.1 mA; V _{CC} = 1.1 V | - | - | 0.3 × V _{CC} | V |
| | | I _O = 1.7 mA; V _{CC} = 1.4 V | - | - | 0.37 | V |
| | | I _O = 1.9 mA; V _{CC} = 1.65 V | - | - | 0.35 | V |
| | | I _O = 2.3 mA; V _{CC} = 2.3 V | - | - | 0.33 | V |
| | | I _O = 3.1 mA; V _{CC} = 2.3 V | - | - | 0.45 | V |
| | | I _O = 2.7 mA; V _{CC} = 3.0 V | - | - | 0.33 | V |
| I _O = 4.0 mA; V _{CC} = 3.0 V | - | - | 0.45 | V | | |
| I _I | input leakage current | V _I = GND to 3.6 V; V _{CC} = 0 V to 3.6 V | - | - | ±0.5 | μA |
| I _{OFF} | power-off leakage current | V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V | - | - | ±0.5 | μA |
| ΔI _{OFF} | additional power-off leakage current | V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V to 0.2 V | - | - | ±0.6 | μA |
| I _{CC} | supply current | V _I = GND or V _{CC} ; I _O = 0 A; V _{CC} = 0.8 V to 3.6 V | - | - | 0.9 | μA |
| ΔI _{CC} | additional supply current | V _I = V _{CC} - 0.6 V; I _O = 0 A; V _{CC} = 3.3 V | - | - | 50 | μA |
| T_{amb} = -40 °C to +125 °C | | | | | | |
| V _{OH} | HIGH-level output voltage | V _I = V _{T+} or V _{T-} | | | | |
| | | I _O = -20 μA; V _{CC} = 0.8 V to 3.6 V | V _{CC} - 0.11 | - | - | V |
| | | I _O = -1.1 mA; V _{CC} = 1.1 V | 0.6 × V _{CC} | - | - | V |
| | | I _O = -1.7 mA; V _{CC} = 1.4 V | 0.93 | - | - | V |
| | | I _O = -1.9 mA; V _{CC} = 1.65 V | 1.17 | - | - | V |
| | | I _O = -2.3 mA; V _{CC} = 2.3 V | 1.77 | - | - | V |
| | | I _O = -3.1 mA; V _{CC} = 2.3 V | 1.67 | - | - | V |
| | | I _O = -2.7 mA; V _{CC} = 3.0 V | 2.40 | - | - | V |
| I _O = -4.0 mA; V _{CC} = 3.0 V | 2.30 | - | - | V | | |
| V _{OL} | LOW-level output voltage | V _I = V _{T+} or V _{T-} | | | | |
| | | I _O = 20 μA; V _{CC} = 0.8 V to 3.6 V | - | - | 0.11 | V |
| | | I _O = 1.1 mA; V _{CC} = 1.1 V | - | - | 0.33 × V _{CC} | V |
| | | I _O = 1.7 mA; V _{CC} = 1.4 V | - | - | 0.41 | V |
| | | I _O = 1.9 mA; V _{CC} = 1.65 V | - | - | 0.39 | V |
| | | I _O = 2.3 mA; V _{CC} = 2.3 V | - | - | 0.36 | V |
| | | I _O = 3.1 mA; V _{CC} = 2.3 V | - | - | 0.50 | V |
| | | I _O = 2.7 mA; V _{CC} = 3.0 V | - | - | 0.36 | V |
| I _O = 4.0 mA; V _{CC} = 3.0 V | - | - | 0.50 | V | | |
| I _I | input leakage current | V _I = GND to 3.6 V; V _{CC} = 0 V to 3.6 V | - | - | ±0.75 | μA |
| I _{OFF} | power-off leakage current | V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V | - | - | ±0.75 | μA |

Table 8. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|------------------|--------------------------------------|---|-----|-----|------------|---------|
| ΔI_{OFF} | additional power-off leakage current | V_I or $V_O = 0$ V to 3.6 V; $V_{CC} = 0$ V to 0.2 V | - | - | ± 0.75 | μA |
| I_{CC} | supply current | $V_I = GND$ or V_{CC} ; $I_O = 0$ A; $V_{CC} = 0.8$ V to 3.6 V | - | - | 1.4 | μA |
| ΔI_{CC} | additional supply current | $V_I = V_{CC} - 0.6$ V; $I_O = 0$ A; $V_{CC} = 3.3$ V | - | - | 75 | μA |

11. Dynamic characteristics

Table 9. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 13](#).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +125 °C | | | Unit |
|--------|-----------|------------|-------|--------------------|-----|-------------------|-------------|--------------|------|
| | | | Min | Typ ^[1] | Max | Min | Max (85 °C) | Max (125 °C) | |

$C_L = 5$ pF

| | | | | | | | | | |
|----------|-------------------|---|---------------------|------|------|-----|------|------|----|
| t_{pd} | propagation delay | A, B and C to Y; see Figure 12 | [2] | | | | | | |
| | | $V_{CC} = 0.8$ V | - | 22.8 | - | - | - | - | ns |
| | | $V_{CC} = 1.1$ V to 1.3 V | 2.8 | 6.6 | 12.9 | 2.6 | 13.1 | 13.3 | ns |
| | | $V_{CC} = 1.4$ V to 1.6 V | 2.4 | 4.8 | 7.6 | 2.4 | 8.3 | 8.6 | ns |
| | | $V_{CC} = 1.65$ V to 1.95 V | 2.1 | 4.0 | 6.3 | 2.0 | 6.9 | 7.3 | ns |
| | | $V_{CC} = 2.3$ V to 2.7 V | 2.0 | 3.2 | 4.6 | 1.8 | 5.1 | 5.4 | ns |
| | | $V_{CC} = 3.0$ V to 3.6 V | 1.9 | 2.9 | 3.9 | 1.6 | 4.2 | 4.4 | ns |

$C_L = 10$ pF

| | | | | | | | | | |
|----------|-------------------|---|---------------------|------|------|-----|------|------|----|
| t_{pd} | propagation delay | A, B and C to Y; see Figure 12 | [2] | | | | | | |
| | | $V_{CC} = 0.8$ V | - | 26.4 | - | - | - | - | ns |
| | | $V_{CC} = 1.1$ V to 1.3 V | 3.2 | 7.4 | 14.5 | 3.0 | 14.9 | 15.2 | ns |
| | | $V_{CC} = 1.4$ V to 1.6 V | 2.7 | 5.4 | 8.7 | 2.7 | 9.4 | 9.8 | ns |
| | | $V_{CC} = 1.65$ V to 1.95 V | 2.5 | 4.5 | 7.1 | 2.3 | 7.9 | 8.3 | ns |
| | | $V_{CC} = 2.3$ V to 2.7 V | 2.4 | 3.8 | 5.3 | 2.2 | 5.9 | 6.2 | ns |
| | | $V_{CC} = 3.0$ V to 3.6 V | 2.3 | 3.5 | 4.6 | 1.9 | 4.9 | 5.1 | ns |

$C_L = 15$ pF

| | | | | | | | | | |
|----------|-------------------|---|---------------------|------|------|-----|------|------|----|
| t_{pd} | propagation delay | A, B and C to Y; see Figure 12 | [2] | | | | | | |
| | | $V_{CC} = 0.8$ V | - | 29.9 | - | - | - | - | ns |
| | | $V_{CC} = 1.1$ V to 1.3 V | 3.6 | 8.3 | 16.1 | 3.3 | 16.7 | 17.0 | ns |
| | | $V_{CC} = 1.4$ V to 1.6 V | 3.0 | 5.9 | 9.7 | 3.0 | 10.5 | 11.0 | ns |
| | | $V_{CC} = 1.65$ V to 1.95 V | 2.8 | 5.0 | 7.9 | 2.5 | 8.7 | 9.2 | ns |
| | | $V_{CC} = 2.3$ V to 2.7 V | 2.7 | 4.2 | 5.9 | 2.5 | 6.6 | 6.9 | ns |
| | | $V_{CC} = 3.0$ V to 3.6 V | 2.5 | 3.9 | 5.2 | 2.2 | 5.5 | 5.8 | ns |

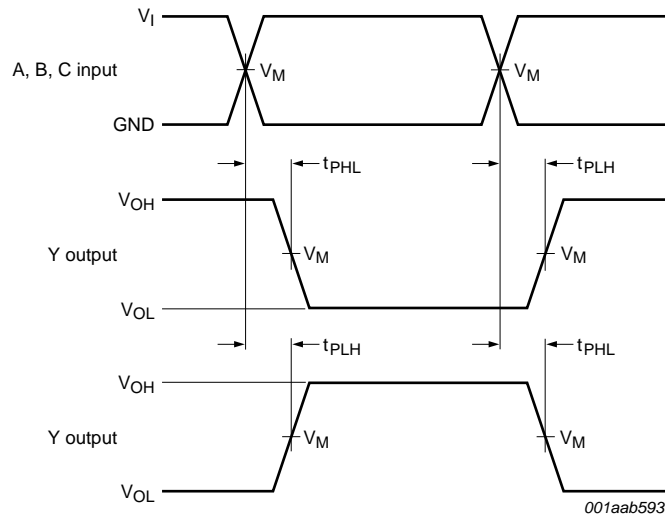
Table 9. Dynamic characteristics ...continued

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 13](#).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +125 °C | | | Unit |
|---|-------------------------------|---|------------------------|--------------------|------|-------------------|-------------|--------------|------|
| | | | Min | Typ ^[1] | Max | Min | Max (85 °C) | Max (125 °C) | |
| C_L = 30 pF | | | | | | | | | |
| t _{pd} | propagation delay | A, B and C to Y; see Figure 12 | [2] | | | | | | |
| | | V _{CC} = 0.8 V | - | 38.0 | - | - | - | - | ns |
| | | V _{CC} = 1.1 V to 1.3 V | 4.5 | 10.5 | 20.8 | 4.1 | 21.9 | 24.1 | ns |
| | | V _{CC} = 1.4 V to 1.6 V | 3.8 | 7.5 | 12.2 | 3.8 | 13.5 | 14.1 | ns |
| | | V _{CC} = 1.65 V to 1.95 V | 3.4 | 6.3 | 10.0 | 3.1 | 11.2 | 11.9 | ns |
| | | V _{CC} = 2.3 V to 2.7 V | 3.4 | 5.3 | 7.5 | 3.1 | 8.4 | 8.9 | ns |
| | | V _{CC} = 3.0 V to 3.6 V | 3.3 | 5.0 | 6.6 | 2.9 | 7.1 | 7.4 | ns |
| C_L = 5 pF, 10 pF, 15 pF and 30 pF | | | | | | | | | |
| C _{PD} | power dissipation capacitance | f _i = 1 MHz; V _I = GND to V _{CC} | [3][4] | | | | | | |
| | | V _{CC} = 0.8 V | - | 2.7 | - | - | - | - | pF |
| | | V _{CC} = 1.1 V to 1.3 V | - | 2.8 | - | - | - | - | pF |
| | | V _{CC} = 1.4 V to 1.6 V | - | 3.0 | - | - | - | - | pF |
| | | V _{CC} = 1.65 V to 1.95 V | - | 3.2 | - | - | - | - | pF |
| | | V _{CC} = 2.3 V to 2.7 V | - | 3.8 | - | - | - | - | pF |
| | | V _{CC} = 3.0 V to 3.6 V | - | 4.4 | - | - | - | - | pF |

- [1] All typical values are measured at nominal V_{CC}.
- [2] t_{pd} is the same as t_{PLH} and t_{PHL}.
- [3] All specified values are the average typical values over all stated loads.
- [4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:
 f_i = input frequency in MHz;
 f_o = output frequency in MHz;
 C_L = load capacitance in pF;
 V_{CC} = supply voltage in V;
 N = number of inputs switching;
 Σ(C_L × V_{CC}² × f_o) = sum of the outputs.

12. Waveforms



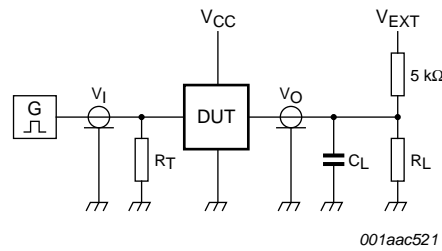
Measurement points are given in [Table 10](#).

V_{OL} and V_{OH} are typical output voltage drop that occur with the output load.

FIG 12. Input A, B and C to output Y propagation delay times

Table 10. Measurement points

| Supply voltage | Output | Input | | |
|----------------|---------------------|---------------------|----------|---------------|
| V_{CC} | V_M | V_M | V_I | $t_r = t_f$ |
| 0.8 V to 3.6 V | $0.5 \times V_{CC}$ | $0.5 \times V_{CC}$ | V_{CC} | ≤ 3.0 ns |



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Test data is given in [Table 11](#).

Definitions for test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to the output impedance Z_o of the pulse generator.

V_{EXT} = External voltage for measuring switching times.

Fig 13. Test circuit for measuring switching times

Table 11. Test data

| Supply voltage | Load | | V_{EXT} | | |
|----------------|------------------------------|--------------|-----------------------|-----------------------|-----------------------|
| V_{CC} | C_L | R_L [1] | t_{PLH} , t_{PHL} | t_{PZH} , t_{PHZ} | t_{PZL} , t_{PLZ} |
| 0.8 V to 3.6 V | 5 pF, 10 pF, 15 pF and 30 pF | 5 kΩ or 1 MΩ | open | GND | $2 \times V_{CC}$ |

[1] For measuring enable and disable times $R_L = 5 \text{ k}\Omega$, for measuring propagation delays, setup and hold times and pulse width $R_L = 1 \text{ M}\Omega$.

13. Transfer characteristics

Table 12. Transfer characteristics

Voltages are referenced to GND (ground = 0 V; for test circuit see [Figure 13](#)).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +125 °C | | | Unit |
|-----------------|--|---|-------|-----|------|-------------------|-------------|--------------|------|
| | | | Min | Typ | Max | Min | Max (85 °C) | Max (125 °C) | |
| V _{T+} | positive-going threshold voltage | see Figure 14 and Figure 15 | | | | | | | |
| | | V _{CC} = 0.8 V | 0.30 | - | 0.60 | 0.30 | 0.60 | 0.62 | V |
| | | V _{CC} = 1.1 V | 0.53 | - | 0.90 | 0.53 | 0.90 | 0.92 | V |
| | | V _{CC} = 1.4 V | 0.74 | - | 1.11 | 0.74 | 1.11 | 1.13 | V |
| | | V _{CC} = 1.65 V | 0.91 | - | 1.29 | 0.91 | 1.29 | 1.31 | V |
| | | V _{CC} = 2.3 V | 1.37 | - | 1.77 | 1.37 | 1.77 | 1.80 | V |
| | | V _{CC} = 3.0 V | 1.88 | - | 2.29 | 1.88 | 2.29 | 2.32 | V |
| V _{T-} | negative-going threshold voltage | see Figure 14 and Figure 15 | | | | | | | |
| | | V _{CC} = 0.8 V | 0.10 | - | 0.60 | 0.10 | 0.60 | 0.60 | V |
| | | V _{CC} = 1.1 V | 0.26 | - | 0.65 | 0.26 | 0.65 | 0.65 | V |
| | | V _{CC} = 1.4 V | 0.39 | - | 0.75 | 0.39 | 0.75 | 0.75 | V |
| | | V _{CC} = 1.65 V | 0.47 | - | 0.84 | 0.47 | 0.84 | 0.84 | V |
| | | V _{CC} = 2.3 V | 0.69 | - | 1.04 | 0.69 | 1.04 | 1.04 | V |
| | | V _{CC} = 3.0 V | 0.88 | - | 1.24 | 0.88 | 1.24 | 1.24 | V |
| V _H | hysteresis voltage (V _{T+} - V _{T-}); see Figure 14 , Figure 15 , Figure 16 and Figure 17 | | | | | | | | |
| | | V _{CC} = 0.8 V | 0.07 | - | 0.50 | 0.07 | 0.50 | 0.50 | V |
| | | V _{CC} = 1.1 V | 0.08 | - | 0.46 | 0.08 | 0.46 | 0.46 | V |
| | | V _{CC} = 1.4 V | 0.18 | - | 0.56 | 0.18 | 0.56 | 0.56 | V |
| | | V _{CC} = 1.65 V | 0.27 | - | 0.66 | 0.27 | 0.66 | 0.66 | V |
| | | V _{CC} = 2.3 V | 0.53 | - | 0.92 | 0.53 | 0.92 | 0.92 | V |
| | | V _{CC} = 3.0 V | 0.79 | - | 1.31 | 0.79 | 1.31 | 1.31 | V |

14. Waveforms transfer characteristics

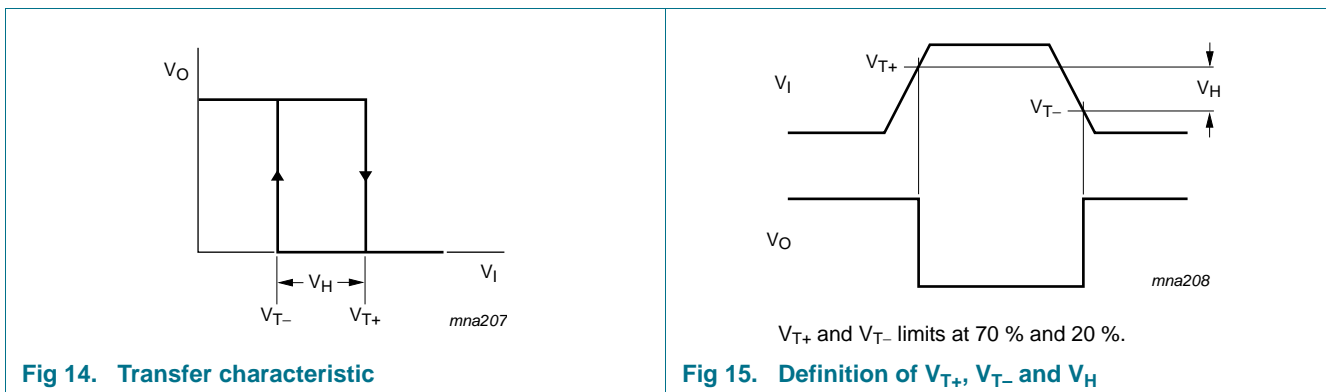


Fig 14. Transfer characteristic

Fig 15. Definition of V_{T+}, V_{T-} and V_H

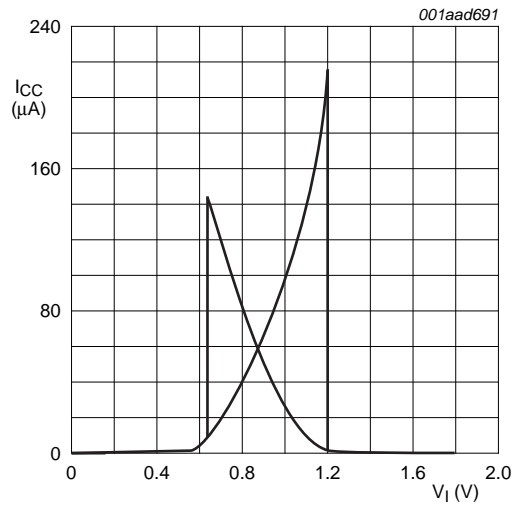


Fig 16. Typical transfer characteristics; V_{CC} = 1.8 V

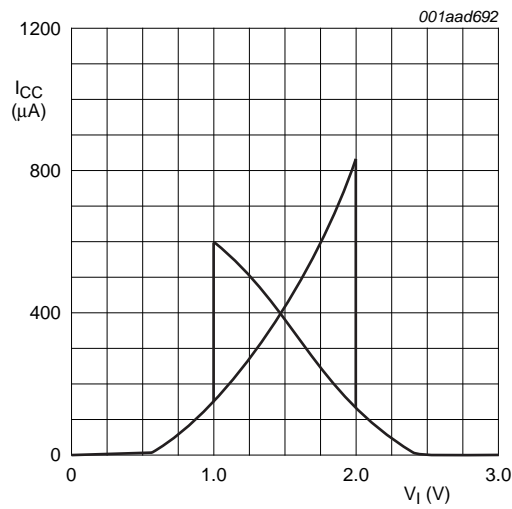


Fig 17. Typical transfer characteristics; V_{CC} = 3.0 V

15. Package outline

Plastic surface-mounted package; 6 leads

SOT363

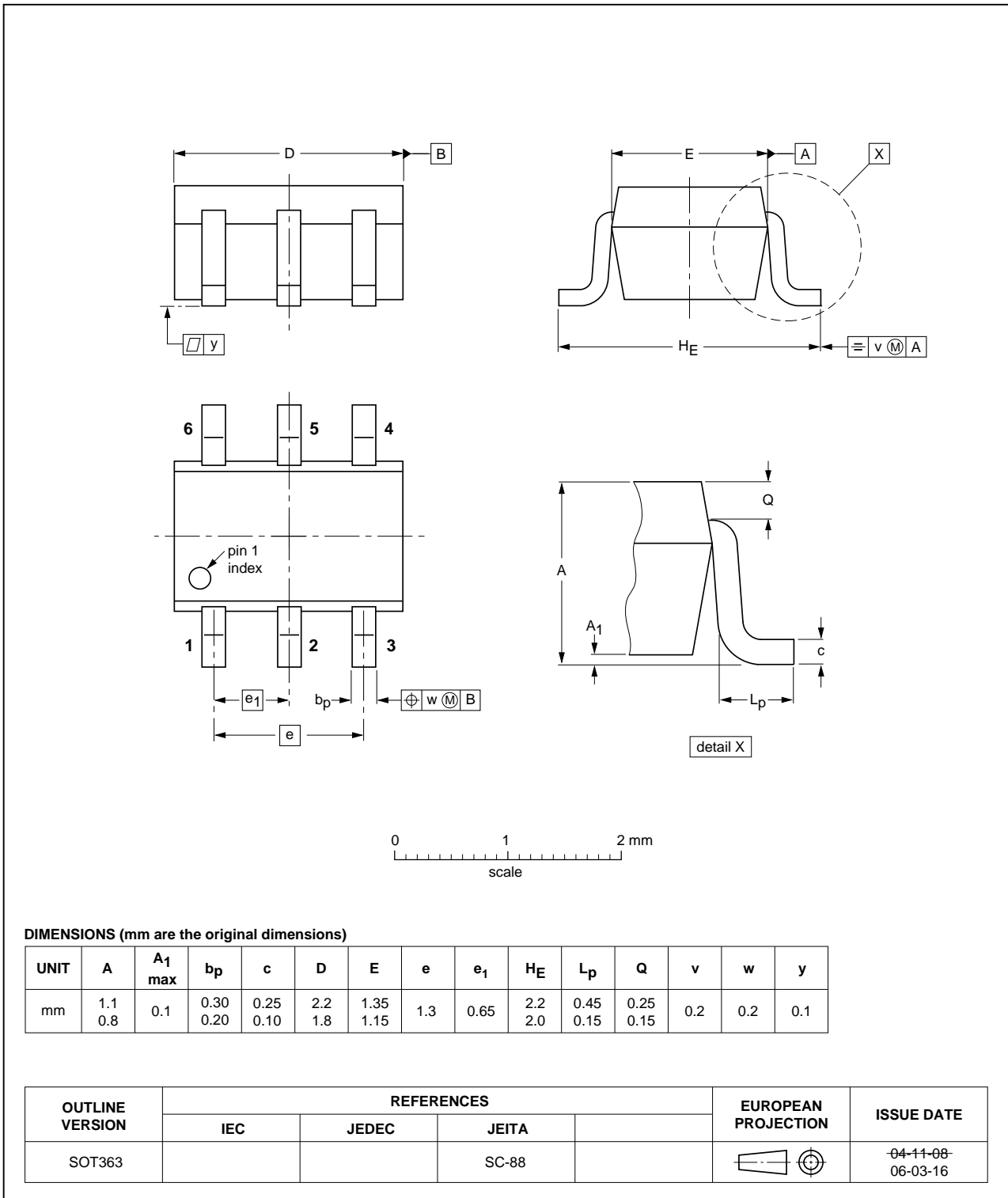


Fig 18. Package outline SOT363 (SC-88)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886

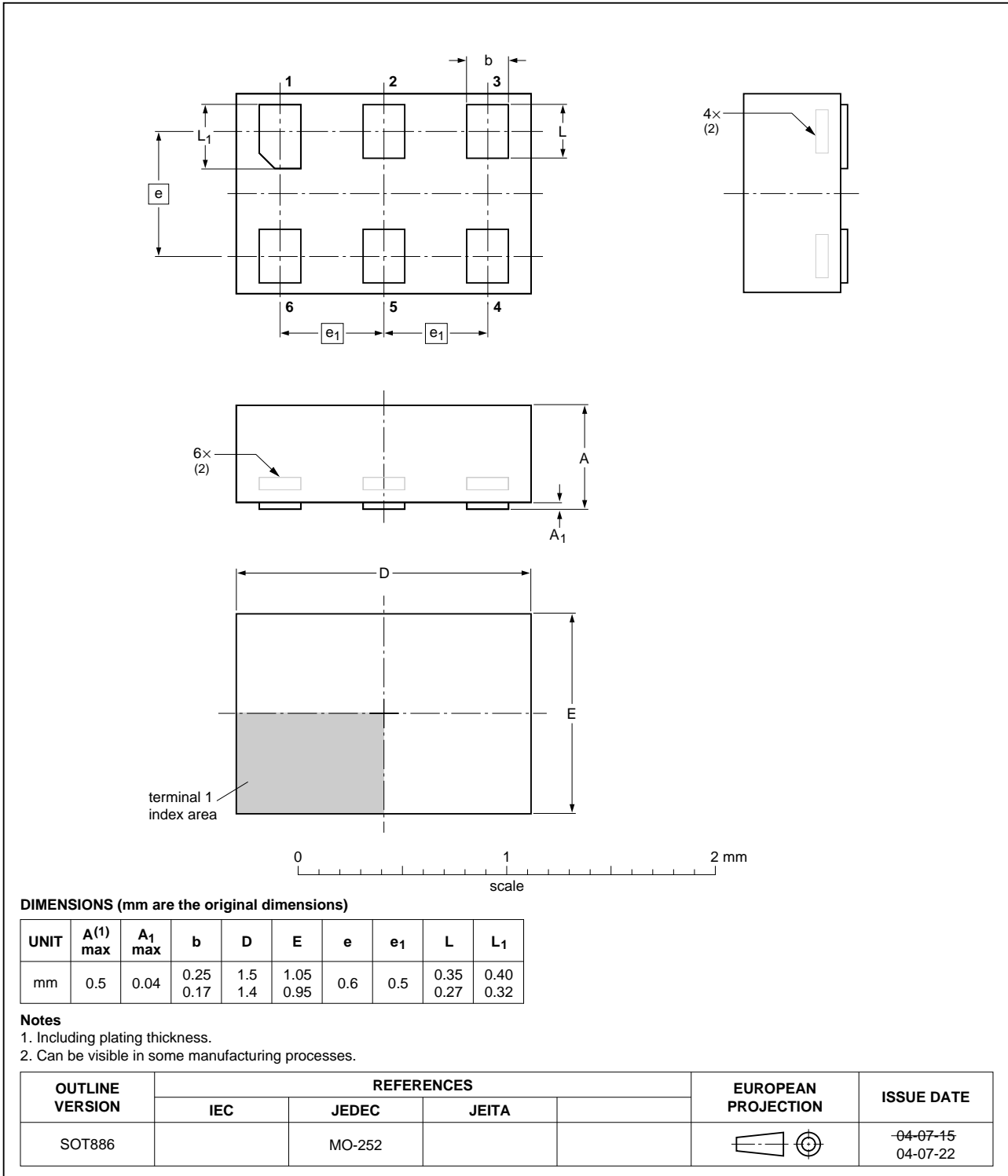


Fig 19. Package outline SOT886 (XSON6)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1 x 0.5 mm

SOT891

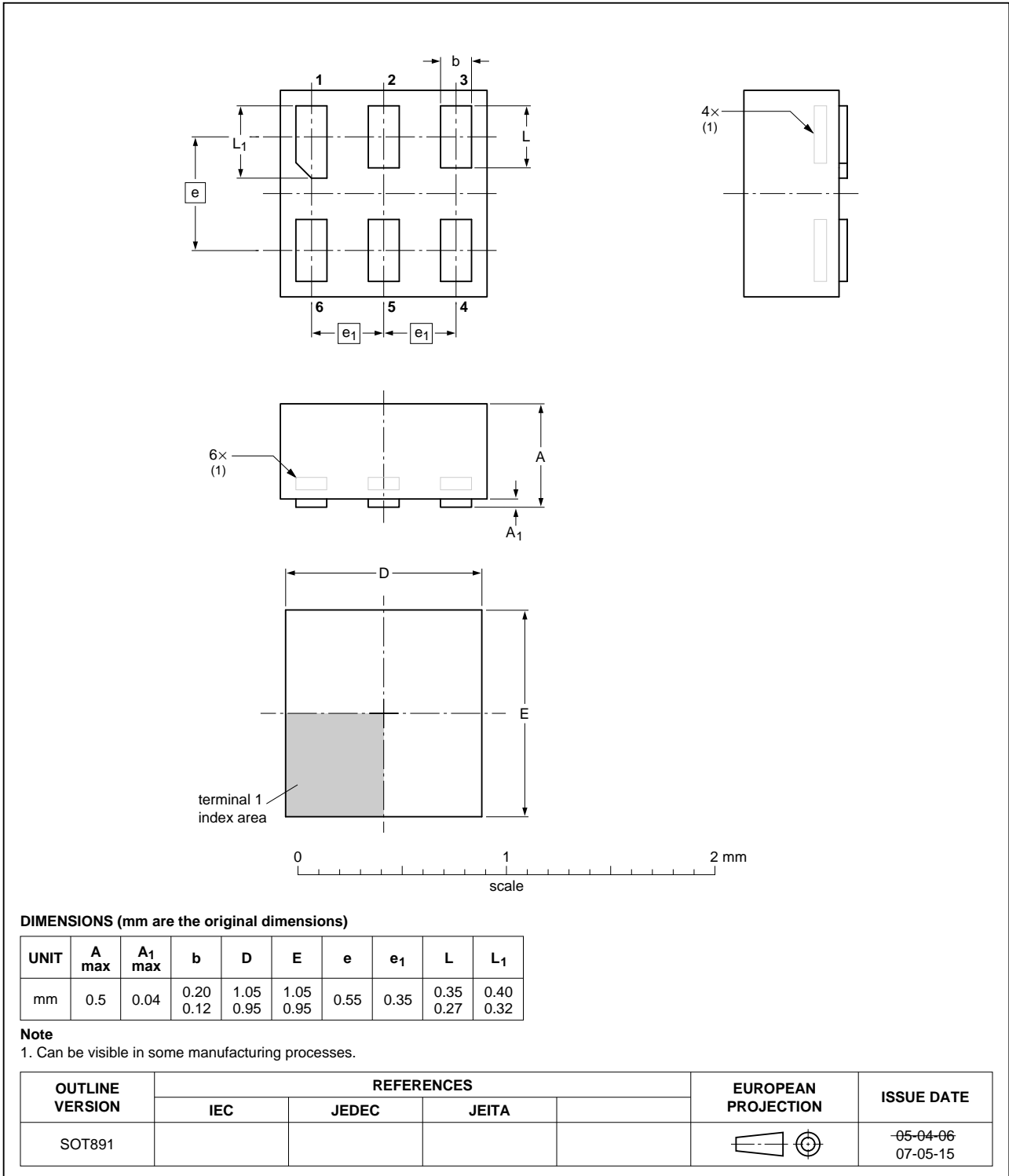


Fig 20. Package outline SOT891 (XSON6)

**XSON6: extremely thin small outline package; no leads;
6 terminals; body 0.9 x 1.0 x 0.35 mm**

SOT1115

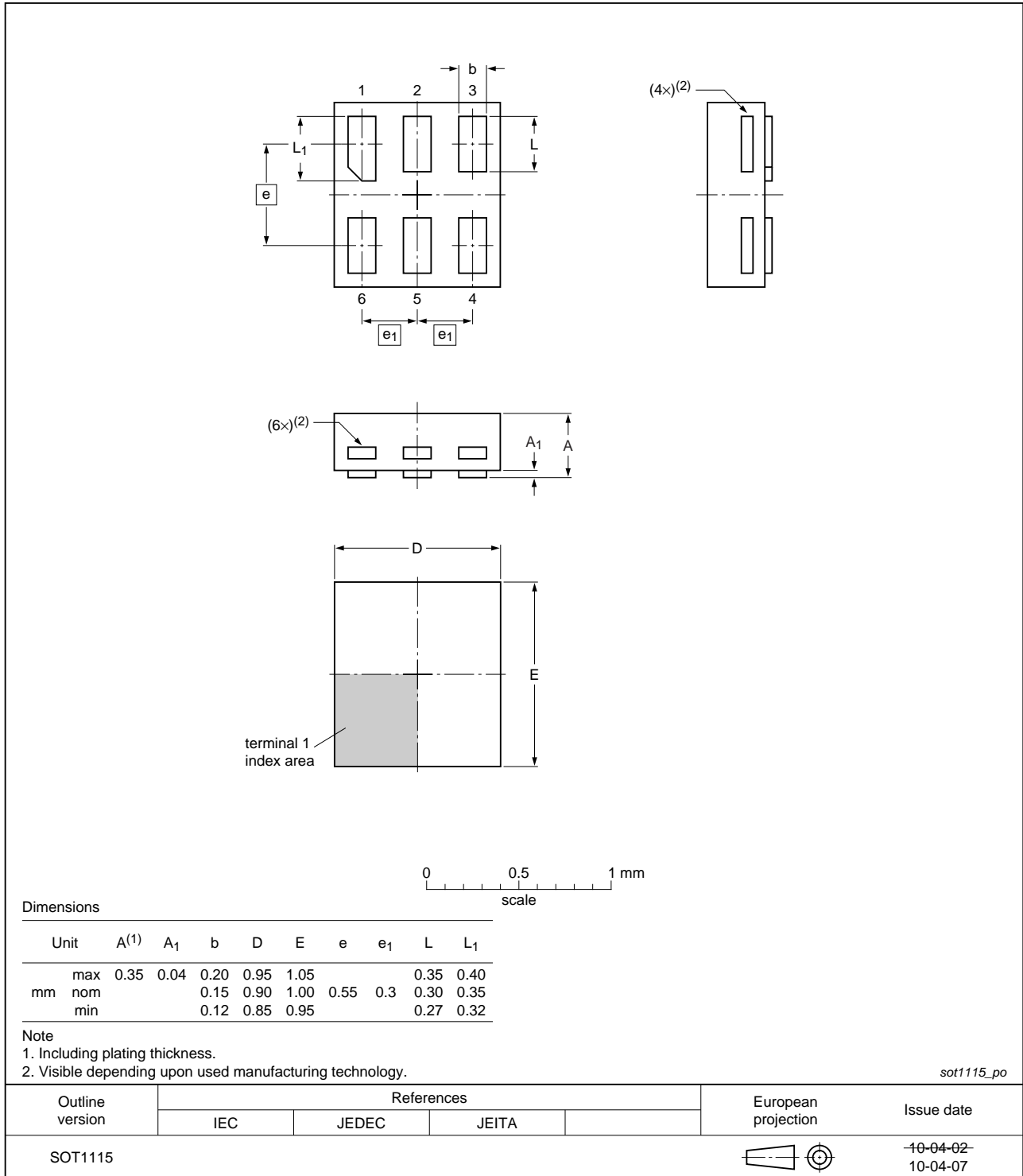


Fig 21. Package outline SOT1115 (XSON6)

**XSON6: extremely thin small outline package; no leads;
6 terminals; body 1.0 x 1.0 x 0.35 mm**

SOT1202

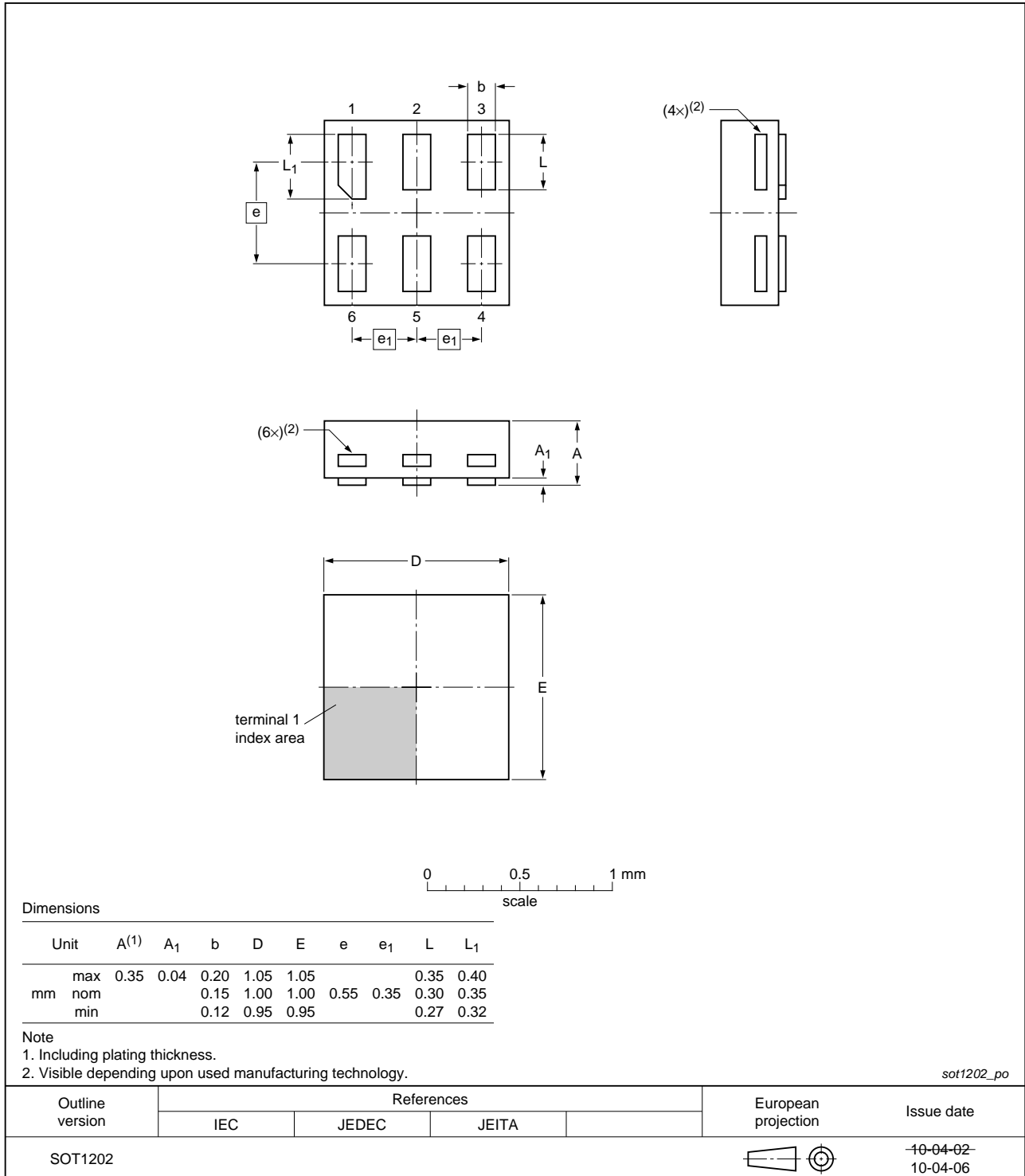


Fig 22. Package outline SOT1202 (XSON6)

16. Abbreviations

Table 13. Abbreviations

| Acronym | Description |
|---------|-------------------------|
| CDM | Charged Device Model |
| DUT | Device Under Test |
| ESD | ElectroStatic Discharge |
| HBM | Human Body Model |
| MM | Machine Model |

17. Revision history

Table 14. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|----------------|--|--------------------|---------------|---------------|
| 74AUP1G58 v.5 | 20111129 | Product data sheet | - | 74AUP1G58 v.4 |
| Modifications: | <ul style="list-style-type: none">• Legal pages updated. | | | |
| 74AUP1G58 v.4 | 20101011 | Product data sheet | - | 74AUP1G58 v.3 |
| 74AUP1G58 v.3 | 20090622 | Product data sheet | - | 74AUP1G58 v.2 |
| 74AUP1G58 v.2 | 20090326 | Product data sheet | - | 74AUP1G58 v.1 |
| 74AUP1G58 v.1 | 20070131 | Product data sheet | - | - |

18. Legal information

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| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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